



October 27, 2017

Subject: RoHS Compliance

Dear Sir:

Please be advised that the Texas Instruments Plug-In Power Devices(s) identified below are compliant with RoHS Directive 2011/65/EU. Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH.

PN	Exemption
PTH08T240WAD	7a, 7(c)-I
PTH08t240WAH	7a,7(c)-I

For RoHS definitions please refer to TI website or attached information.

A handwritten signature in black ink, appearing to read 'Joseph K. Pudlo'.

Joseph K. Pudlo  
Product Reliability Manager  
Texas Instruments Plug-In Power  
27715 Diehl Road  
Warrenville, IL 60555

## Lead-free (Pb-free)

Due to worldwide environmental concerns, the need for lead-free devices in electronic components and systems continues to receive significant attention within the semiconductor and electronics industries.

TI is committed to working with customers to offer products that meet their specific needs in this area. Nickel/Palladium (Ni/Pd) finish, a lead-free alternative, was introduced to the IC market by TI in 1989. By 2000, these products moved to a Nickel/Palladium/Gold (Ni/Pd/Au).

Today TI's lead-free products use Ni/Pd/Au or annealed matte tin (Sn) for leadframe type packages and Tin/Silver/Copper (Sn/Ag/Cu) for ball grid array (BGA) types of products. All of these products meet the current European Union (EU) RoHS thresholds for lead, cadmium, mercury, hexavalent chromium, polybrominated biphenyls (PBBs) and polybrominated diphenyl ethers (PBDEs).

A few of TI's products are RoHS compliant with the use of an EU RoHS Exemption for lead, specifically:

- 7(a): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
- 7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors (e.g. piezoelectric devices), or in a glass or ceramic matrix compound
- 7(c) IV: Lead in PZT-based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
- 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

TI's remaining products using lead are required by customers and out of scope of EU RoHS, such as military and space products. For more information on specific packages or part numbers visit the TI Website.